

## Product Change Notification - KSRA-09NLQI319

**Date:** 27 Feb 2018

**Product Category:** 16-Bit - Microcontrollers and Digital Signal Controllers; Interface- Serial Peripherals; 8-bit PIC Microcontrollers

**Notification subject:** CCB 2910 and 2910.001 Final Notice: Qualification of CuPdAu bond wire in selected products of the 150K and 160K wafer technology available in 28L QFN package at NSEB assembly site

**Notification text:** **PCN Status:**  
Final notification

**PCN Type:**  
Manufacturing Change

**Microchip Parts Affected:**

Please open the attachments found in the attachments field below labeled as PCN\_#\_Affected\_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

**Description of Change:**

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 150K and 160K wafer technology available in 28L QFN package at NSEB assembly site

**Pre Change:**

Using gold (Au) bond wire, 8200T and 8600 die attach and G770HCD and G700LTD mold compound material.

**Post Change:**

Using palladium coated copper with gold flash (CuPdAu) bond wire, 8600 die attach and G700LTD mold compound material.

**Pre and Post Change Summary:**

	Pre Change		Post Change
<b>Assembly Site</b>	UTAC Thai Limited LTD. (NSEB)		UTAC Thai Limited LTD. (NSEB)
<b>Wire material</b>	Au Wire		CuPdAu Wire
<b>Die attach material</b>	8200T	8600	8600
<b>Molding compound material</b>	G770HCD	G700LTD	G700LTD
<b>Lead frame material</b>	EFTEC-64T		EFTEC-64T

**Impacts to Data Sheet:**

None

**Change Impact:**

None

**Reason for Change:**

To improve manufacturability and qualify CuPdAu bond wire at NSEB assembly site.

**Change Implementation Status:**

In Progress

**Estimated First Ship Date:**

March 27, 2018 (date code: 1813)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts

**Time Table Summary:**

Workweek	April 2017					-->	February 2018					March 2018				
	13	14	15	16	17		05	06	07	08	09	10	11	12	13	
Initial PCN Issue Date					X											
Qual Report Availability										X						
Final PCN Issue Date										X						
Estimated Implementation Date														X		

**Method to Identify Change:**

Traceability code

**Qualification Report:**

Please open the attachments included with this PCN labeled as PCN\_#\_Qual Report.

**Revision History:**

**April 24, 2016:** Issued initial notification.

**February 27, 2018:** Issued final notification. Attached the Qualification Report. Revised the affected parts list. Provided estimated first ship date on March 27, 2018.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

**Attachment(s):**

- [PCN\\_KSRA-09NLQI319\\_Affected\\_CPN.pdf](#)
- [PCN\\_KSRA-09NLQI319\\_Qual Report.pdf](#)
- [PCN\\_KSRA-09NLQI319\\_Affected\\_CPN.xlsx](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

<b>PCN_KSRA-09NLQI319</b>
<b>CATALOG_PART_NBR</b>
DSPIC30F2011-20I/ML
DSPIC30F2011-30I/ML
DSPIC30F2012-20E/ML
DSPIC30F2012-20I/ML
DSPIC30F2012-30I/ML
MCP23016-I/ML
MCP23016T-I/ML
MCP23017-E/ML
MCP23017T-E/ML
MCP23S17-E/ML
MCP23S17T-E/ML
PIC16F570-E/ML
PIC16F570-I/ML
PIC16F570T-I/ML
PIC16F627A-E/ML
PIC16F627A-I/ML
PIC16F627AT-I/ML
PIC16F628A-E/ML
PIC16F628A-I/ML
PIC16F628AT-E/ML
PIC16F628AT-I/ML
PIC16F648A-E/ML
PIC16F648A-I/ML
PIC16F648AT-E/ML
PIC16F648AT-I/ML
PIC16F72-E/ML
PIC16F72-I/ML
PIC16F72T-I/ML
PIC16F737-E/ML
PIC16F737-I/ML
PIC16F737T-I/ML
PIC16F73-E/ML
PIC16F73-I/ML
PIC16F73T-I/ML
PIC16F767-E/ML
PIC16F767-I/ML
PIC16F767T-E/ML
PIC16F767T-I/ML
PIC16F76-I/ML
PIC16F76T-I/ML
PIC16F818-E/ML
PIC16F818-I/ML
PIC16F818T-I/ML

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<b>PCN_KSRA-09NLQI319</b>
<b>CATALOG_PART_NBR</b>
PIC16F819-E/ML
PIC16F819-I/ML
PIC16F819-I/MLTSL
PIC16F819T-E/ML
PIC16F819T-I/ML
PIC16F873A-E/ML
PIC16F873A-I/ML
PIC16F873AT-I/ML
PIC16F876A-E/ML
PIC16F876A-I/ML
PIC16F876AT-E/ML
PIC16F876AT-I/ML
PIC16F87-I/ML
PIC16F882-E/ML
PIC16F882-I/ML
PIC16F882T-I/ML
PIC16F883-E/ML
PIC16F883-I/ML
PIC16F883T-E/ML
PIC16F883T-I/ML
PIC16F883T-I/ML031
PIC16F886-E/ML
PIC16F886-I/ML
PIC16F886T-E/ML
PIC16F886T-I/ML
PIC16F886T-I/MLC06
PIC16F88-E/ML
PIC16F88-I/ML
PIC16F88T-I/ML
PIC16F913-E/ML
PIC16F913-I/ML
PIC16F913T-I/ML
PIC16F916-E/ML
PIC16F916-I/ML
PIC16F916T-I/ML
PIC16F916T-I/MLC02
PIC16LF627A-I/ML
PIC16LF627AT-I/ML
PIC16LF628A-I/ML
PIC16LF628AT-I/ML
PIC16LF648A-I/ML
PIC16LF648AT-I/ML
PIC16LF72-I/ML

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<b>PCN_KSRA-09NLQI319</b>
<b>CATALOG_PART_NBR</b>
PIC16LF72-I/ML026
PIC16LF72T-I/ML
PIC16LF737-I/ML
PIC16LF73-I/ML
PIC16LF73T-I/ML
PIC16LF767-I/ML
PIC16LF767T-I/ML
PIC16LF76-I/ML
PIC16LF76T-I/ML057
PIC16LF818-I/ML
PIC16LF818T-I/ML
PIC16LF819-I/ML
PIC16LF819T-I/ML
PIC16LF873A-I/ML
PIC16LF873AT-I/ML
PIC16LF876A-I/ML
PIC16LF876AT-I/ML
PIC16LF87-I/ML
PIC16LF88-I/ML
PIC16LF88T-I/ML
PIC18F1220-E/ML
PIC18F1220-H/ML
PIC18F1220-I/ML
PIC18F1220T-I/ML
PIC18F1230-E/ML
PIC18F1230-I/ML
PIC18F1230-I/MLXXX
PIC18F1320-E/ML
PIC18F1320-H/ML
PIC18F1320-I/ML
PIC18F1320T-I/ML
PIC18F1330-E/ML
PIC18F1330-I/ML
PIC18F1330-I/MLXXX
PIC18F1330-ICD/ML
PIC18F2221-E/ML
PIC18F2221-I/ML
PIC18F2221T-I/ML
PIC18F2321-E/ML
PIC18F2321-I/ML
PIC18F2410-E/ML
PIC18F2410-I/ML
PIC18F2420-E/ML

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<b>PCN_KSRA-09NLQI319</b>
<b>CATALOG_PART_NBR</b>
PIC18F2420-I/ML
PIC18F2420T-E/ML
PIC18F2420T-I/ML
PIC18F2423-E/ML
PIC18F2423-I/ML
PIC18F2423T-I/ML
PIC18F2510-E/ML
PIC18F2510-I/ML
PIC18F2510T-E/ML
PIC18F2510T-I/ML
PIC18F2520-E/ML
PIC18F2520-I/ML
PIC18F2520T-I/ML
PIC18F2523-E/ML
PIC18F2523-I/ML
PIC18F2523T-I/ML
PIC18LF1220-I/ML
PIC18LF1230-I/ML
PIC18LF1320-I/ML
PIC18LF1320T-I/ML
PIC18LF1330-I/ML
PIC18LF2221-I/ML
PIC18LF2321-I/ML
PIC18LF2321T-I/ML
PIC18LF2410-I/ML
PIC18LF2410T-I/ML
PIC18LF2420-I/ML
PIC18LF2420T-I/ML
PIC18LF2420T-I/ML025
PIC18LF2423-I/ML
PIC18LF2423T-I/ML
PIC18LF2510-I/ML
PIC18LF2510T-I/ML
PIC18LF2520-I/ML
PIC18LF2520T-I/ML
PIC18LF2523-I/ML
PIC18LF2523T-I/ML